

Features

- 30% lighter than the same size aluminium heat sinks
- Reduced EMI issues
- Excellent mouldability

Applications

Switching power supplies, AC motors, microprocessors and LED cooling.

Spreadfast thermally conductive engineering plastic has been developed for its light weight, mouldability and EMI issue reducing properties. Heat sinks using this plastic have a 30% reduced weight when compared with aluminium.

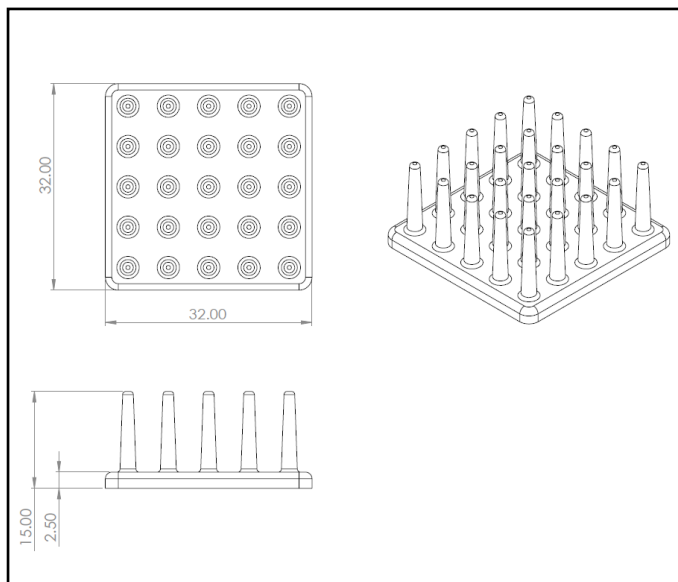
The material has excellent mouldability for injection moulding and much higher production yield than aluminium die casting. This is particularly suitable for camera and electronics housing with built in heat dispersing design.

Four popular geometries have been designed for various applications. Special designs are available.

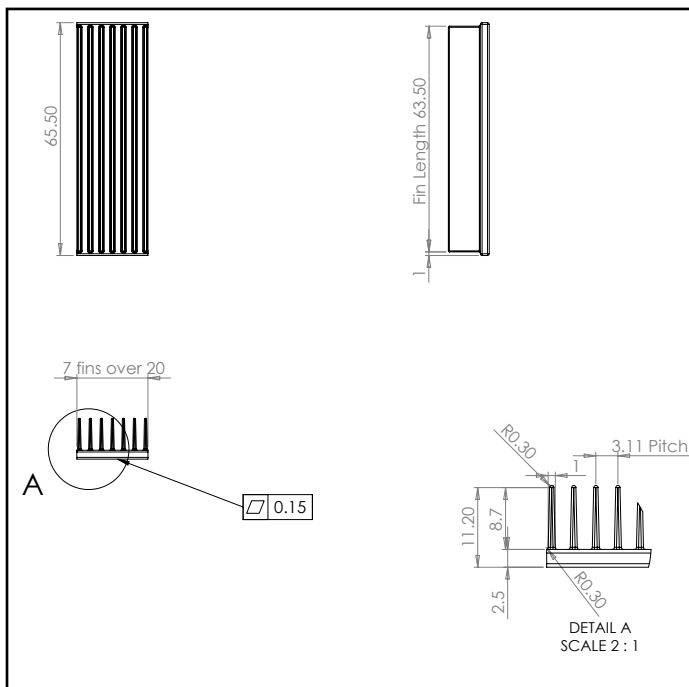
MPN	Title	Length mm	Width mm	Height mm
SFPLAS-6202-15P	Heatsink, plastic, 62x62x15mm, pin	65	65	20
SFPLAS-65x62-11L	Heatsink, plastic, 65x62x11mm, line	65	65	15
SFPLAS-65x20-11L	Heatsink, plastic, 65x20x11mm, line	65	25	15
SFPLAS-3002-15P	Heatsink, plastic, 30x30x15mm, pin	35	35	20

	Property	Units	Test	Value
Physical	Material	N/A	-	Thermally conductive plastic
	Colour	-	Visual	Black
	Melt index	g/10min	ISO 1133	4
	Specific gravity	g/cm ³	ISO 1183	1.45
	Shrinkage	LFM	ISO 294	0.1
Mechanical	Tensile strength	MPa	ISO 527	55
	Flexural strength	MPa	ISO 178	80
	Flexural modulus	MPa	ISO 178	15800
	Impact strength, notched	kJ/m ²	ISO 180	2.5-3.5
Thermal	Thermal conductivity (through thickness)	W/mK	ASTM E1461	5
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	Heat deflection temp.	°C	ASTM D648	150
	Flame retardancy @ 1mm thick sample	-	UL 94	V-0
Electrical	Dielectric constant @1MHz	E	ASTM D150	4.5
	Volume resistivity	Ωm	ASTM D257	10000

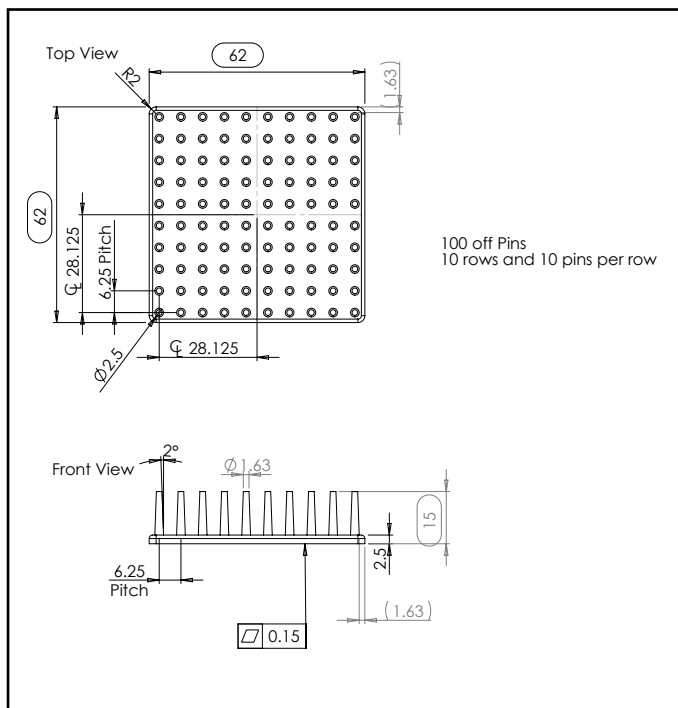
Drawings



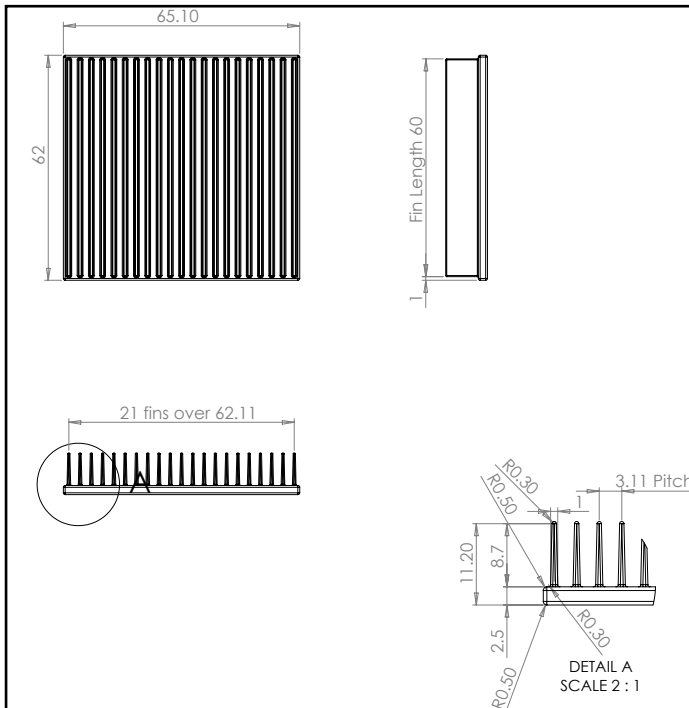
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SFPLAS-6020-9L

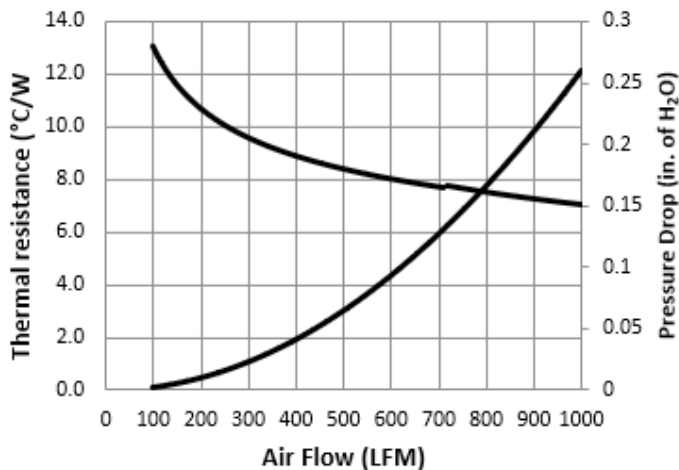


SFPLAS-6202-15P

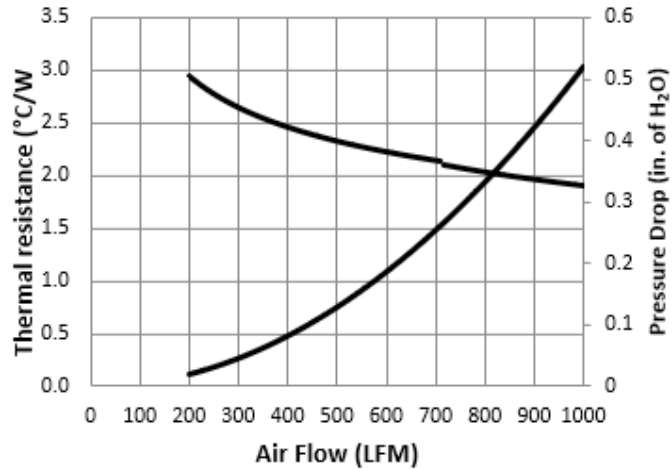


SFPLAS-65x62-11L

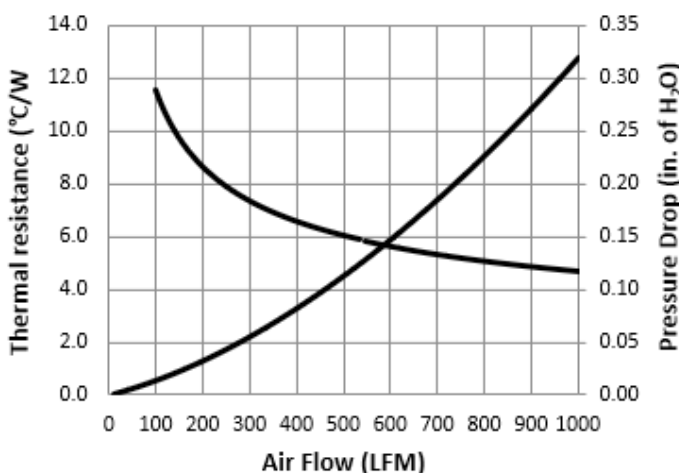
Graphs



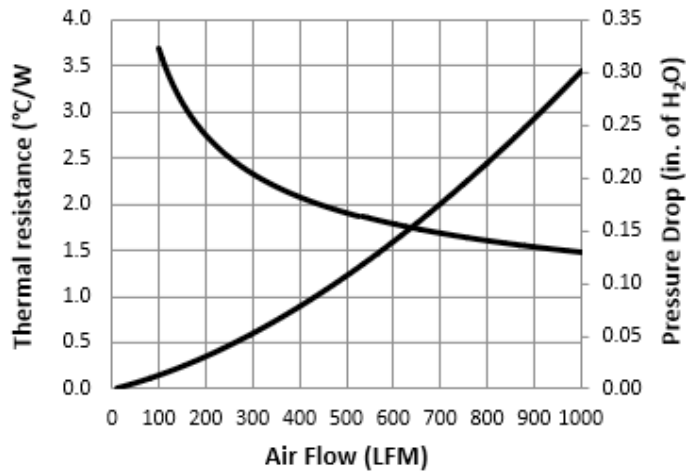
SFPLAS-3002-15P



SFPLAS-6202-15P



SFPLAS-65x20-11L



SFPLAS-65x62-11L